



WDS-850 BGA Repair machine Optical Alignment Automatic Rework station for PC&phone motherboard chip repair

Our Product Introduction

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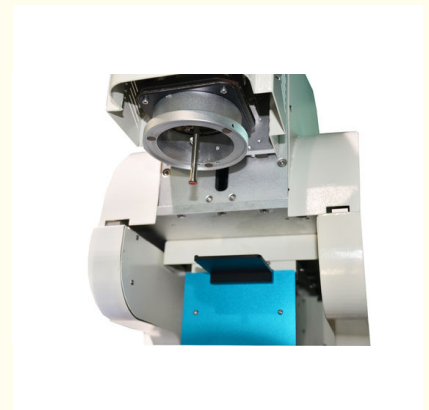
Basic Information

- Place of Origin: China
- Brand Name: WDS
- Certification: CE
- Model Number: WDS-850
- Minimum Order Quantity: 1 UNIT
- Packaging Details: Wooden case
- Delivery Time: 8-15 working days
- Payment Terms: T/T, Western Union, MoneyGram
- Supply Ability: 150 UNITS PER MONTH



Product Specification

- Warranty: 1 Year
- Weight: 200KG
- Voltage: AC 220V
- Current: 50/60hz
- Dimensions: L970*W7000*H830mm
- Total Power: 8400W
- PCB Size: Max680*550mm Min 10*10 Mm
- BGA Chip Size: Max120*120mm Min 0.8*0.8mm
- Power: Ac220v $\pm 10\%$, 50/60hz
- Heater Power: Upper Temp.one 1600w, second Temp.zone 1600w, IR Temp.zone 5000w
- Alignment System: Optical Prism + HD Camera
- Highlight: **WDS-850 BGA Repair Machine,
phone motherboard BGA Repair Machine,
WDS-850 BGA Repair machine**



More Images



Product Description

HD display Vacuum adsorption WDS-850 Optical alignment automatic repair equipment

Excellent performance features

Multi-language menu interface

Automatic feeding device

X/Y axis can be controlled by rocker, fast operation

Imported high-definition CCD(2 million pixels) optical alignment system

High precision temperature control system, accurate temperature control system, accurate temperature control



Specification

WDS-850

Power	AC 220V±10 50Hz	Total power	7600W
Up heater power	Max 1200W	Mount max load	800G
Down heater power	Max 1200W	IR power	5000W (2000W controlled)
Max PCB size	630*480mm	Min PCB size	10×10mm
Chip magnification	2-50 multiple	Temp. interface	5个
Suit PCB thickness	0.5-8mm	Mount accuracy	±0.01mm
Suit chip size	0.8*0.8~80*80mm	Chip min spacing	0.15mm
Dimensions	L970*W700*H830mm	Weight	About 210KG

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HD optical alignment and intelligent control

The integrated design of hot air head and mounting head has the functions of automatic mounting, automatic welding and automatic disassembly. High precision K-type thermocouple (KSENSOR) cLOSED Loop control, up and down independent temperature measurement, temperature control accuracy up to ± 1 degree, Over-temperature protection alarm function, software encryption and anti-stay function.



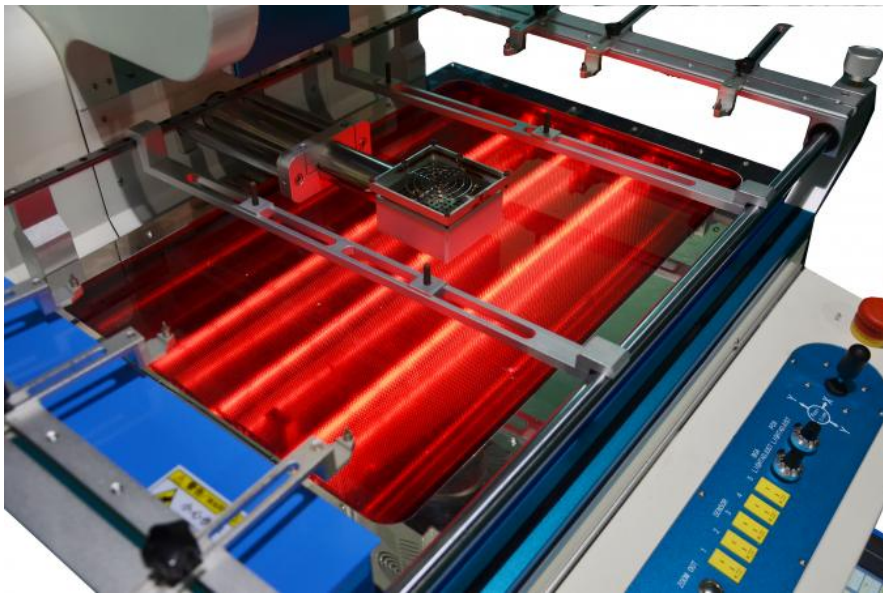
HD display

High-definition imported CCD(2 million pixels) digital imaging, automatic optical zoom system, automatic precision alignment control system with laser red dot, using 15 inch high-definition industrial display screen display.



Vacuum adsorption and preheating platform

The upper heating head is equipped with a vacuum suction pipe for chip adsorption. The bottom preheating platform adopts imported excellent heating materials(infrared gold-plated light tube)+anti-flash thermostatic glass (temperature resistance up to 1800°C). The preheating area is up to 500*420mm. The preheating platform, splint device and cooling system can be moved as a whole in the X direction. Make PCB positioning and folding welding more safe and convenient.



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Specification

Model	WDS-850
Total power supply	8400W
Upper heating power supply	1600W
Lower heating power supply	1600W
IR heating power supply	5000W(2000W controlled)
Power supply	220V, 50/60Hz
Maximum	680*550mm
Minimum	10*10mm
Temperature measuring interfaces	5pcs

Chip zoom in and zoom out	2-50/times
The PCB thickness	0.5 8mm
Apply chip size	0.8*0.8 120*120mm
Applicable minimum chip spacing	0.15mm
Maximum mouting load	300g
Mounting precision	±0.01mm
Machine dimension	L970*W700*H830mm
Machine weight	200KG



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